

b) a head interconnect circuit secured to the suspension means, the head interconnect circuit including a conductive material; and

c) a slider scale package, the slider scale package including the slider/MR head and a flex circuit, the flex circuit electrically connected to the slider/MR head, secured to the back of the slider/MR head, and arranged and configured with a plurality of interconnect pads disposed at the back of the slider/MR head, wherein the plurality of interconnect pads are electrically connected to the conductive material of the head interconnect circuit.

29. (NEW) The HGA of claim 28, wherein the flex circuit includes a first end, a second end, and a conductive material extending from the first end to the second end.

30. (NEW) The HGA of claim 29, wherein the plurality of interconnect pads are located at the first end of the flex circuit, the slider/MR head includes a plurality of bond pads, and the conductive material of the flex circuit is electrically connected to the interconnect pads at the first end and to the plurality of bond pads of the slider/MR head at the second end.

31. (NEW) The HGA of claim 30, wherein the flex circuit includes first, second, third, and fourth interconnect pads.

32. (NEW) The HGA of claim 30, wherein the slider/MR head includes first, second, third, and fourth bond pads.

33. (NEW) The HGA of claim 30, wherein the flex circuit includes first, second, third, and fourth interconnect pads and the slider/MR head includes first, second, third, and fourth bond pads, and wherein the first, second, third and fourth interconnect pads of the flex

circuit are electrically connected to the first, second, third and fourth bond pads of the slider/MR head respectively by the conductive material of the flex circuit.

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